

# United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address of MMISSCORE IF PATENTS AND TRAITI MALES washington 100 unit

APPLICATION NO	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO	CONFIRMATION NO
09 686,624	10/12/2000	Jung-Ho Lee	10.253,006	6123
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LEE & STERBA, P.C. 1101 WILSON BOULEVARD SUITE 2000			ENAMINER	
			NGUYEN, KHIEM D	
ARLINGTON, VA 22209			ART UNIT	PAPER NUMBER
			2823	
			DATE MAILED: 12-13-2002	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)
		09/686,624	LEE ET AL
Office Action Summary		Examiner	Art Unit
		Khiem D Nguyen	2823
The MAILIN Period for Reply	IG DATE of this communication	appears on the cover she	et with the correspondence address
A SHORTENED S THE MAILING DA  - Extensions of time may after SIX (6) MONTHS I  - If the period for reply sp - If NO period for reply is - Failure to reply within th - Any reply received by th	TATUTORY PERIOD FOR RETE OF THIS COMMUNICATION be available under the provisions of 37 CFI from the mailing date of this communication secified above is less than thirty (30) days, a specified above, the maximum statutory per set or extended period for reply will, by state office later than three months after the maximum. See 37 CFR 1.704(b).	N. R 1.136(a). In no event, however, m. reply within the statutory minimum riod will apply and will expire SIX (6) atute, cause the application to become	ay a reply be timely filed  of thirty (30) days will be considered timely.  MONTHS from the mailing date of this communication me ABANDONED (35 U.S.C. § 133).
1) Responsive	e to communication(s) filed on	08 October 2002 .	
2a) This action	is <b>FINAL</b> . 2b)⊠	This action is non-final.	
,	cordance with the practice un	•	matters, prosecution as to the merits is 5 C.D. 11, 453 O.G. 213.
4) Claim(s) 10	-12 and 14-28 is/are pending in	the application.	
4a) Of the ab	ove claim(s) is/are with	drawn from consideration	
5) Claim(s) <u>23-</u>	28 is/are allowed.		
6)⊡ Claim(s) <u>10-</u>	12 and 14-22 is/are rejected.		
7) Claim(s)	is/are objected to.		
8) Claim(s) Application Papers	are subject to restriction an	d/or election requirement	
9) The specifica	tion is objected to by the Exam	iner.	
10) The drawing(s	s) filed on is/are: a) a	ccepted or b) objected to	by the Examiner.
	ay not request that any objection t	*	· ·
			disapproved by the Examiner.
	corrected drawings are required in		
12) The oath or d	eclaration is objected to by the	Examiner.	
Priority under 35 U.S.	.C. §§ 119 and 120		
· ·	ment is made of a claim for for	eign priority under 35 U.S	.C. § 119(a)-(d) or (f).
a)	Some * c) ☐ None of:		
_	ed copies of the priority docum		
2.☐ Certifie	ed copies of the priority docum	ents have been received	in Application No
ар	s of the certified copies of the p plication from the International ned detailed Office action for a	Bureau (PCT Rule 17.2(	
14) Acknowledgm	ent is made of a claim for dome	estic priority under 35 U.S	S.C. § 119(e) (to a provisional application)
, —	slation of the foreign language ent is made of a claim for dom	• • • • • • • • • • • • • • • • • • • •	
attachment(s)			
	Cited (PTO-892) n's Patent Drawing Review (PTO-948) e Statement(s) (PTO-1449) Paper No(	5) 🔲 Notic	e of Informal Patent Application (PTO-152)
S. Patent and Trademark Office			Part of Paper No 9

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#### DETAILED ACTION

The indicated allowability of claims 13 and 20-21 is withdrawn in view of the newly discovered reference(s) to Kajiura et al. (U.S. Patent 5,907,382). Rejections based on the newly cited reference(s) follow.

# Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- Claims 10-12 and 14-22 are rejected under 35 U.S.C. 103(a) as being unpatentable over the applicant's admitted prior art (AAPA) of this application in view of Imamura et al. (U.S. Patent 5,738,911), Shibuya et al. (U.S. Patent 6,338,868), Tanaka et al. (U.S. Patent 5,974,666) and Kajiura et al. (U.S. Patent 5,907,382).

AAPA teaches a method of forming a silicon oxide layer comprising (see Description of the Related Art on pages 1-3 of this application):

providing a semiconductor substrate having a stepped portion formed by at least two conductive patterns selected from gate electrodes and metal wiring patterns of a semiconductor device;

coating the semiconductor substrate with a spin-on glass (SOG) composition, curing the SOG layer to form a layer of silicon oxide having a planar surface.

AAPA fails to teach that the spin-on glass (SOG) composition containing perhydropolysilazane having the compound formula -(SiH<sub>2</sub>NH)<sub>n</sub>- wherein n represents a

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positive integer, and main-baking the SOG layer at a temperature within the range of about 400 to about 1,200°C for a second period of time wherein the main-baking is conducted under an atmosphere comprising one ore more components selected from the group consisting of oxygen, water vapor, mixtures of oxygen and water vapor, nitrogen, and mixture thereof, for about 10 to about 180 minutes as recited in present claims 10-12, 22.

Imamura teaches that the silicon oxide layer (SiO<sub>2</sub>) is forming by baking a spin-on glass (SOG) composition containing perhydropolysilazane having the compound formula -(SiH<sub>2</sub>NH)<sub>n</sub>- (n represents a positive integer) in an air atmosphere consisting of oxygen. Wherein the baking of the perhydropolysilazane is conducted by heating at a temperature ranging from 250° C to 500° C for a time ranging from 0.5 to 3 hours. See col. 3, lines 5-34. It would have been obvious to one of ordinary skill in the art to incorporate Imamura's teaching into AAPA's method because in doing so a uniform thin film having a thickness of several angstroms can be obtained. See col. 3, lines 28-30.

Imamura fails to teach that a weight average molecular weight within the range of about 4,000 to about 8,000, and wherein curing the SOG layer comprises pre-baking the SOG layer at a temperature within the range of about 100 to about 500°C for a first period of time as recited in present claims 10-11.

Tanaka teaches that perhydropolysilazane is heated at 150 °C for a period of time under an oxygen atmosphere to produced silicon oxide layer wherein perhydropolysilazane having a weight-averaged molecular weight of 4,000 to 5000. See col. 6, lines 51-63 and col. 12, lines 16-24. It would have been obvious to one of ordinary

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skill in the art to incorporate Tanaka's teaching into Imamura's method because doing so can prevent occurrence of leaking based on uneven electric resistance of an electrically conductive elastic body layer. See col. 2, lines 54-61.

Imamura fails to teach that the molecular weight dispersion is within the range of about 3.0 to about 4.0 as recited in present claim 10.

Shibuya teaches coating the surface of a substrate with a spin-on glass (SOG) composition containing polysilazane compound having the molecular weight dispersion not exceeding 4. See col. 3, line 50 to col. 4, line 8. It would have been obvious to one of ordinary skill in the art to incorporate Shibuya's teaching into Imamura's method because in doing so a coating film having high resistance against formation of cracks to serve as a planarizing layer on the surface of a substrate can be obtained. See col. 1, lines 8-16.

Neither AAPA, Imamura, Shibuya, Tanaka teach a viscosity range of about 1 to about 10 mPa.s as recited in present claim 10.

Kajiura teaches that the viscosity of the perhydropolysilazane is in the range from  $1x10_{-3}$  to  $1x10_{-2}$  pa.s (See col. 13, lines 9-15) It would have been obvious to one of ordinary skill in the art to incorporate Kajiura's teaching into AAPA's method because in doing so a transparent conductive substrate, that has excellent heat resistant characteristic, shock resisting characteristic, chemical resisting characteristic, oxygen barrier characteristic steam barrier characteristic, and scratch resisting characteristic can be obtained (See Abstract).

None of the prior arts teaches the ranges for the thickness of the silicon oxide and silicon nitride layer, the shear rate, the distance between the at least two conductive

patterns, the aspect ratio of the stepped portion, and the contact angle as recited in present claims 10, 14, 16-18, and 20-21.

However, it would have been obvious to one of ordinary skill in the art of making semiconductor devices to determine the workable or optimal ranges for the thickness of the silicon oxide and silicon nitride layer, the distance between the at least two conductive patterns, the aspect ratio of the stepped portion, and the contact angle through routine experimentation and optimization to obtain optimal or desired device performance because the ranges for the thickness of the silicon oxide and silicon nitride layer, the distance between the at least two conductive patterns, the aspect ratio of the stepped portion, and the contact angle are result-effective variables and there is no evidence indicating that the ranges for the thickness of the silicon oxide and silicon nitride layer, the distance between the at least two conductive patterns, the aspect ratio of the stepped portion, and the contact angle are critical and it has been held that it is not inventive to discover the optimum or workable range of a result-effective variable within given prior art conditions by routine experimentation. See MPEP 2144.05.

### Allowable Subject Matter

Claims 23-28 are allowed.

The following is an examiner's statement of reasons for allowance: The prior art taken alone or in combination neither discloses nor makes obvious the instant process of claims as a whole. Specifically, the prior art fails to teach or disclose wherein curing the SOG layer by:

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pre-baking the SOG layer at a temperature within the range of from about 100 to about 500 °C for a first period of time; and main-baking the SOG layer at a temperature within the range of about 900 to about 1000 °C for a second period of time as recited in present independent claims 23, 25, and 27.

## Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Khiem D Nguyen whose telephone number is (703) 306-0210. The examiner can normally be reached on Monday-Friday (8:00 AM - 5:00 PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Chaudhuri Olik can be reached on (703) 306-2794. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 746-9179 for regular communications and (703) 746-9179 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

K.N. December 10, 2002

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